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Cathy M. F. Deald  
Signature

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Brian C. Barker, et al.

Serial No.: 09/527,761

Filed: March 17, 2000

For: **WAFER IDENTIFICATION  
MARK**

: Conf. No.: 3261

: Art Unit: 2876

: Examiner: Lee, S.

: Atty Docket: 21806/0085

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TECHNOLOGY CENTER 2800

**PROPOSED RESPONSE AND AMENDMENT UNDER 37 CFR § 1.111**Commissioner for Patents  
Washington, D.C. 20231

May 30, 2002

Sir:

In response to the Office Action dated January 30, 2002, the period for response having been extended by one (1) month to May 30, 2002, the following amendments and remarks are submitted in connection with the above-identified application:

**IN THE SPECIFICATION:**

Please amend the Specification as follows:

Please replace the paragraph at line 18, page 12 of the Specification with the following replacement paragraph:

--Similarly, the depth of the pits may depend upon where they are formed. Pits formed on an edge of a semiconductor wafer may be formed a much greater distance into the material of